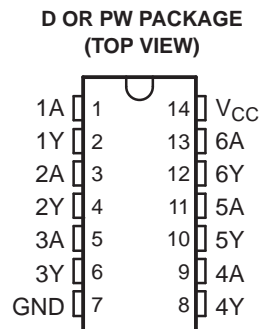


FEATURES

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree ⁽¹⁾**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 V, T_A = 25^\circ C$**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2.3 V at $V_{CC} = 3.3 V, T_A = 25^\circ C$**
- **Supports Mixed-Mode Voltage Operation on All Ports**
- **I_{off} Supports Partial-Power-Down Mode Operation**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



DESCRIPTION/ORDERING INFORMATION

This hex Schmitt-trigger inverter is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV14A contains six independent inverters. This device performs the Boolean function $Y = \bar{A}$.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 105°C	TSSOP – PW	Tape and reel	SN74LV14ATPWREP	LV14AEP
–55°C to 125°C	SOIC – D	Tape and reel	SN74LV14AMDREP	LV14AEP
	TSSOP – PW	Tape and reel	SN74LV14AMPWREP	LV14AEP

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
H	L
L	H



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74LV14A-EP HEX SCHMITT-TRIGGER INVERTER

SCLS499C–MAY 2003–REVISED JUNE 2006

LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	7	V
V _I	Input voltage range ⁽²⁾	-0.5	7	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	7	V
V _O	Output voltage range ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current		-20	mA
		V _I < 0		
I _{OK}	Output clamp current		-50	mA
		V _O < 0		
I _O	Continuous output current		±25	mA
		V _O = 0 to V _{CC}		
	Continuous current through V _{CC} or GND		±50	mA
θ _{JA}	Thermal impedance ⁽⁴⁾	D package	133.5	°C/W
		PW package	113	
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT	
V_{CC}	Supply voltage	2	5.5	V	
V_{IH}	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5	V	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	$V_{CC} \times 0.7$		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC} \times 0.7$		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$V_{CC} \times 0.7$		
V_{IL}	Low-level input voltage	$V_{CC} = 2\text{ V}$	0.5	V	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	$V_{CC} \times 0.3$		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC} \times 0.3$		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$V_{CC} \times 0.3$		
V_I	Input voltage	0	5.5	V	
V_O	Output voltage	0	V_{CC}	V	
I_{OH}	High-level output current	$V_{CC} = 2\text{ V}$	-50	μA	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-2	mA	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	-6		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-12		
I_{OL}	Low-level output current	$V_{CC} = 2\text{ V}$	50	μA	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2	mA	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	6		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	12		
T_A	Operating free-air temperature	SN74LV14AT	-40	105	$^{\circ}\text{C}$
		SN74LV14AM	-55	125	

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74LV14A-EP HEX SCHMITT-TRIGGER INVERTER

SCLS499C – MAY 2003 – REVISED JUNE 2006

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	SN74LV14AT			SN74LV14AM			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{T+} Positive-going threshold		2.5 V			1.75			1.78	V
		3.3 V			2.31			2.31	
		5 V			3.5			3.5	
V _{T-} Negative-going threshold		2.5 V	0.75			0.75			V
		3.3 V	0.99			0.97			
		5 V	1.5			1.5			
ΔV _T Hysteresis (V _{T+} – V _{T-})		2.5 V	0.25		1	0.25		1	V
		3.3 V	0.33		1.32	0.33		1.37	
		5 V	0.5		2	0.5		2	
V _{OH}	I _{OH} = –50 μA	2 V to 5.5 V	V _{CC} – 0.1			V _{CC} – 0.1			V
	I _{OH} = –2 mA	2.3 V	2			2			
	I _{OH} = –6 mA	3 V	2.48			2.48			
	I _{OH} = –12 mA	4.5 V	3.8			3.8			
V _{OL}	I _{OL} = 50 μA	2 V to 5.5 V				0.1			V
	I _{OL} = 2 mA	2.3 V				0.4			
	I _{OL} = 6 mA	3 V				0.44			
	I _{OL} = 12 mA	4.5 V				0.55			
I _I	V _I = V _{CC} or GND	0 to 5.5 V				±1			μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V				20			μA
I _{off}	V _I or V _O = 0 to 5.5 V	0 V				5			μA
C _i	V _I = V _{CC} or GND	3.3 V	2.3			2.3			pf
		5 V	2.3			2.3			

Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
t _{pd}	A	Y	C _L = 50 pF	9.6	16.3		1	20.4	ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
t _{pd}	A	Y	C _L = 50 pF	6.7	10.6		1	14	ns

Noise Characteristics⁽¹⁾
 $V_{CC} = 3.3\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$

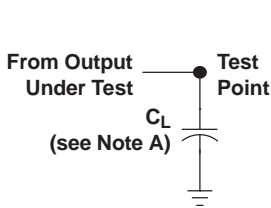
PARAMETER		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}	-0.1	-0.8		V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3.1		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

(1) Characteristics are for surface-mount packages only.

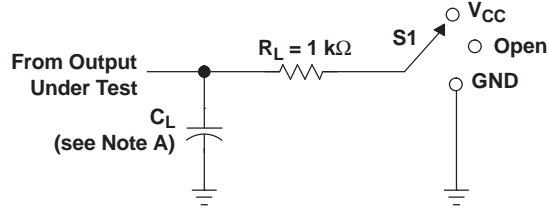
Operating Characteristics
 $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 10\text{ MHz}$	3.3 V	8.8	pF
			5 V	9.6	

PARAMETER MEASUREMENT INFORMATION

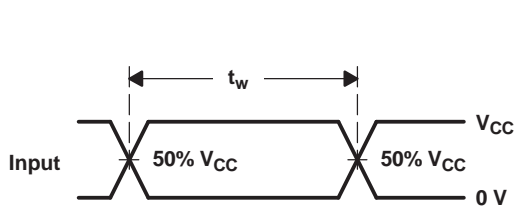


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

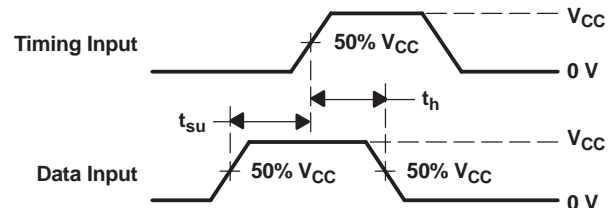


LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

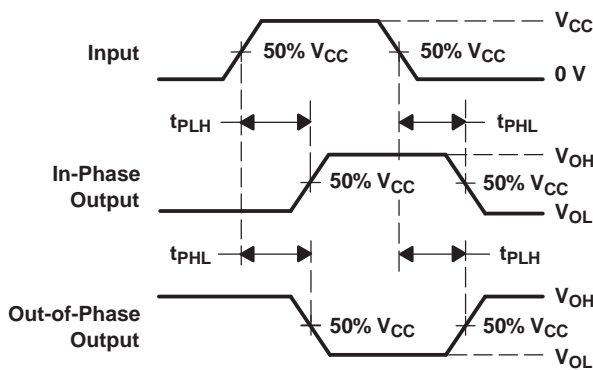
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}



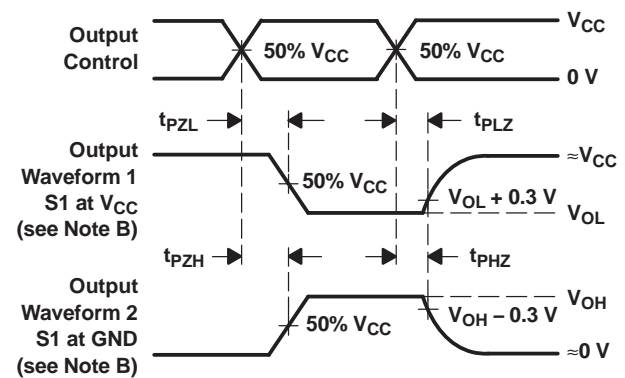
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 D. The outputs are measured one at a time, with one input transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PHL} and t_{PLH} are the same as t_{pd} .
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV14AMDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14AMPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14AMPWREPG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ATPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03662-01XE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03662-02XE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03662-02YE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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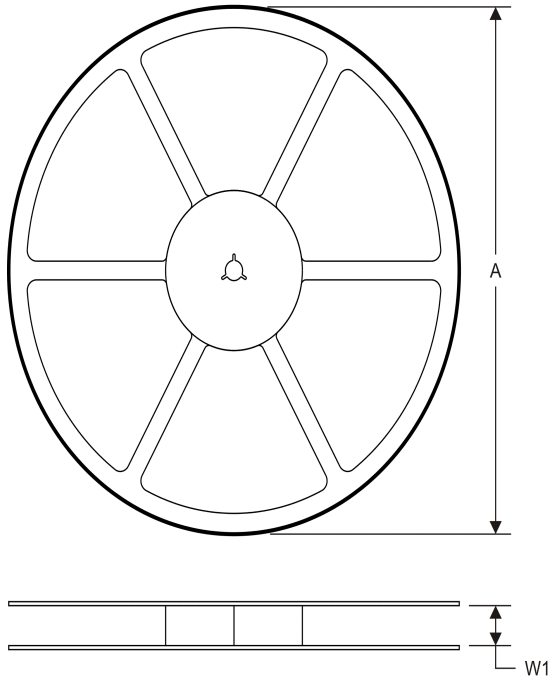
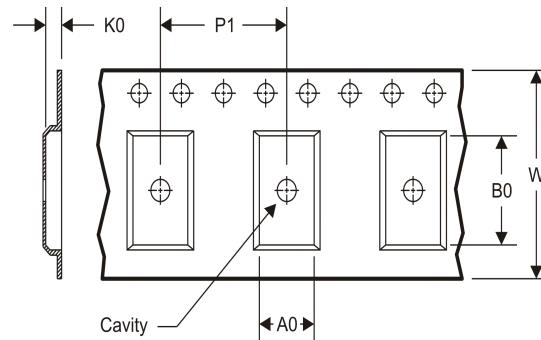
OTHER QUALIFIED VERSIONS OF SN74LV14A-EP :

- Catalog: [SN74LV14A](#)
- Automotive: [SN74LV14A-Q1](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV14AMDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV14AMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV14ATPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV14AMDREP	SOIC	D	14	2500	367.0	367.0	38.0
SN74LV14AMPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74LV14ATPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

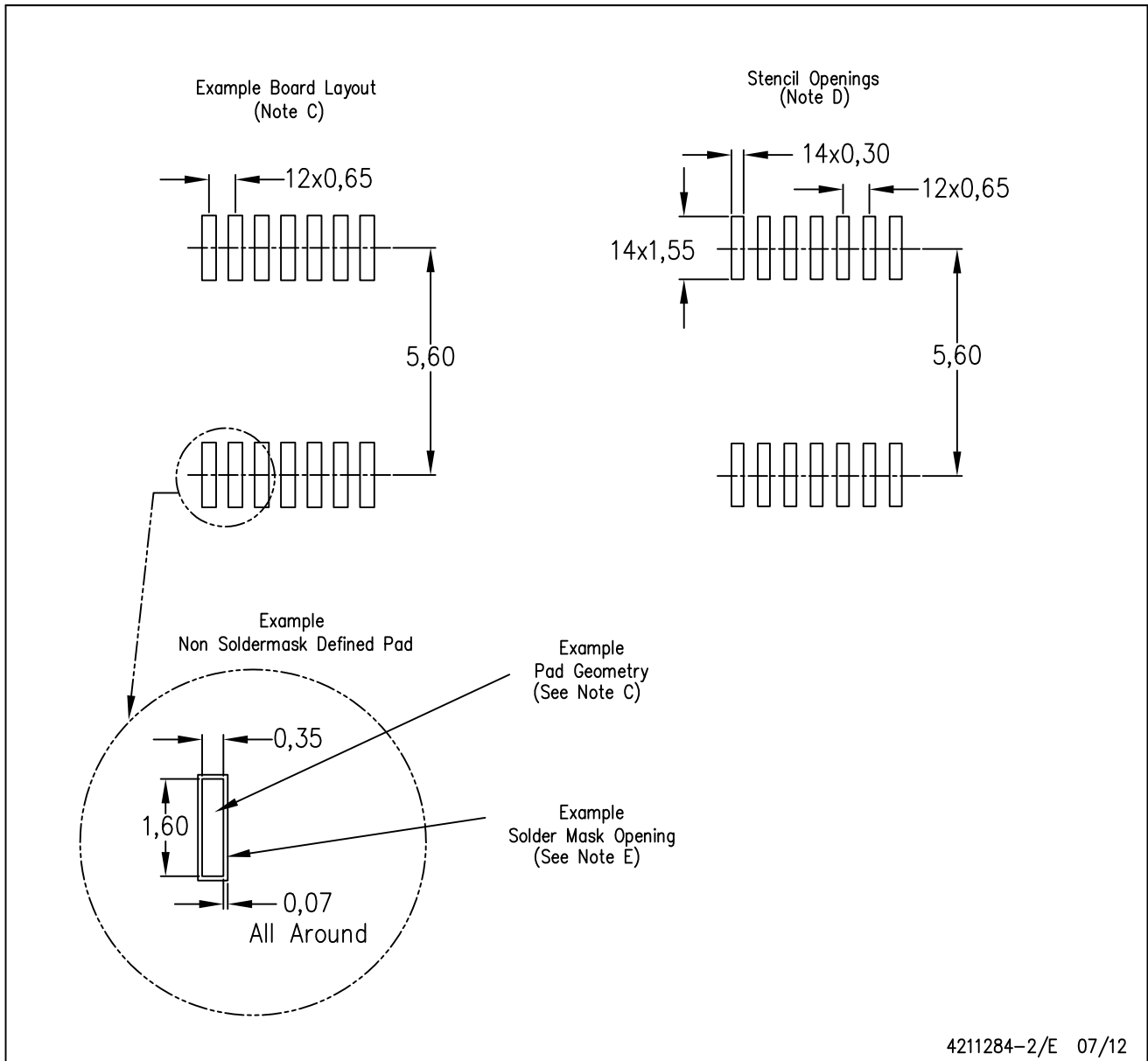


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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